



RADSOK® Power to Board

The Amphenol Industrial Global Operations RADSOK® solution offers options for high current single-point connections with a compact footprint design that can supply up to 120 Amps to the board. The hyperbolic grid contact provides more surface area with many points of contact for heat dissipation at the pin and socket interface. This lowers temperature rise and reduces potential failures. RADSOK® Power-to-Board products are designed to be applied manually by press-fit or by a re-flow solder process eliminating the need for additional wires and/or special crimp tools.

RADSOK® PowerBlok™ provides a high current single-point connection of up to 70 Amps to the PCB utilizing our custom 3.0mm RADSOK® design. The compliant pins are press-fit into the board to secure a solid connection and even current flow. The radial design ensures many points of contact, reduces failure modes, and eliminates burn-outs and possible stress fractures.

RADSOK® RADSSERT™ provides a high power to board interconnect in a small package. The RADSSERT™ brings power to the board from busbars suspended above the board and all of the board components. Pins from the busbar plug into the RADSOK's® which are installed by press fitting the RADSOK® into the RADSSERT™.

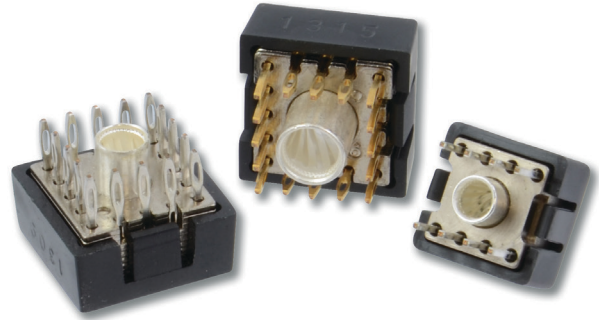
RADSOK® PGY™ is a right angle, co-planar or orthogonal card edge connector series available in 2.4mm, 3.6mm and 5.7mm contact sizes. The 5.7mm is the highest current board level product rated to 120 amperes. Connection to the board is through a solder reflow process. The busbar pin will mate horizontally with the RADSOK® slightly above the board.

RADSOK® RadStack™ was designed to address the need for high current and small foot prints for PCB mezzanine applications. The RadStack™ is low-profile, 10mm to 50mm in any size increment using press fit attachment with a current range of 35A to 120A.



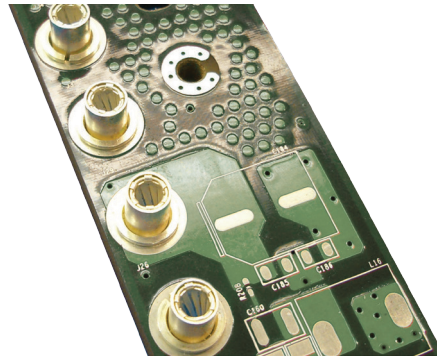
RADSOK® PowerBlok™

- High power to board interconnect in a small package
- Compact footprint 15.7mm x 15.7mm
- RADSOK® 2.4mm, 3.0mm & 3.6mm (35A-60A-70A)
- Backplane power interface with compliant pins for power
- Touchproof cover
- Hyperbolic socket design ensures many points of contact
- Reduces failure modes, eliminates burn outs
- No threaded fasteners
- No special crimp tools required
- Eliminates possible stress fractures in board
- Faster through-put
- RoHS compliant



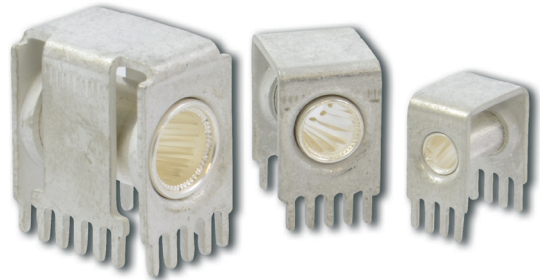
RADSOK® RADSSERT™

- High power to board interconnect in a small package
- Hyperbolic socket design ensures many points of contact
- Solder version or pre-loaded RADSSERTs™ are installed during board fabrication
- RADSSERT™ 2.4mm (35A), 3.0mm (60A), 3.6mm (70A) 5.7mm (120A)
- No special crimp tools required
- No threaded fasteners
- Eliminates risk of PTH cracking or delamination in board
- Faster through-put
- RoHS compliant



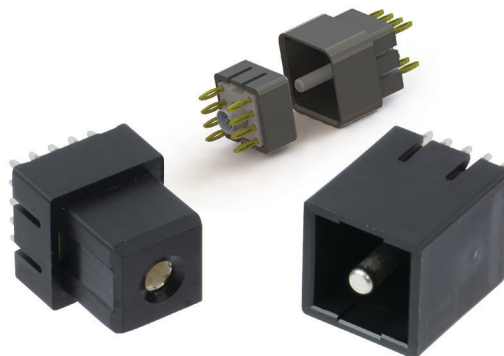
RADSOK® PGY™

- Orthogonal, co-planar & right angle connections between PCBs or PCB to bus bar
- Compact footprint
- Legs of the PGY distribute high power evenly
- 2.4mm carries up to 35 Amps
- 3.0mm carries up to 60 Amps
- 3.6mm carries up to 70 Amps
- 4.8mm carries up to 100 Amps
- 5.7mm carries up to 120 Amps
- No threaded fasteners
- No special crimp tools required
- Faster through-put
- RoHS compliant



RADSOK® RadStack™

- Mezzanine connection between parallel PCBs
- Compact footprint
- Low-profile, 10mm to 50mm in any size increment
- 2.4mm carries up to 35 Amps
- 3.0mm carries up to 60 Amps
- 3.6mm carries up to 70 Amps
- 4.8mm carries up to 100 Amps
- 5.7mm carries up to 120 Amps
- Pressfit
- Faster through-put
- RoHS compliant



Notice: Specifications are subject to change without notice. Contact your nearest Amphenol Corporation Sales Office for the latest specifications. All statements, information and data given herein are believed to be accurate and reliable but are presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suggestions concerning possible use of our products are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should assume that all safety measures are indicated or that other measures may not be required. Specifications are typical and may not apply to all connectors.

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